

PATENT APPLICATION
Attorney Docket: 54364**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

Applicant: Gupta, et al.
Serial No.: 09/847,667
Filed: 5/1/2001
For: Method for Bonding Wafers to
Produce Stacked Integrated
Circuits

Group Art Unit: 2827

Examiner: James Mitchell

PETITION FOR EXTENSION OF TIME

Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Sir:

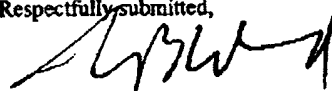
Applicant hereby petitions the Commissioner of Patents and Trademarks under 37 C.F.R. Sect. 1.136(a) to extend the time for response to the Office Action dated 12/4/2003 by 1 month.

The Commissioner is hereby authorized to charge all fees which may be required in this application under 37 C.F.R. Sect. 1.16-1.17 during its entire pendency, or credit any overpayment, to Deposit Account No. 23-0424.

This petition is filed in duplicate.

I hereby certify that this paper is being transmitted via facsimile to: 703-872-9306

Respectfully submitted,



Calvin B. Ward
Registration No. 30,896

Dated: April 1, 2004

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